



<b>Title of Change:</b>	Product Change from LE25S81MC to LE25S81AMD including change of die and assembly site.		
<b>Proposed first ship date:</b>	10 July 2015		
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Ai-Ling.Loh@onsemi.com>		
<b>Samples:</b>	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office.		
<b>Type of notification:</b>	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact &lt;PCN.Support@onsemi.com&gt;.</p>		
<b>Change Part Identification:</b>	It is possible to identify by the top marking.		
<b>Change category(s):</b> <input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Material Change	<input checked="" type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	Regarding this change, refer to the attachment.
<b>Sites Affected:</b> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	<u>Site 1</u> ON Carmona, Philippines	<u>Site 2</u>	
<b>Description and Purpose:</b> <p>This PCN shows replacing existing 8M product to LE25S81MCSxx series of a new product and it is based on continuous product development.</p> <p>The new product uses a new wafer process. Wafer fabrication site, Shanghai Huahong Grace Semiconductor Manufacturing Corporation, does not change.</p> <p>Furthermore, the assembly site change to ON Semiconductor Philippines. Inc. (OSPI) from current Amkor Technology Philippines. The difference between existing product and new product is listed in an attached document.</p> <p>The new product has a function and the characteristic that are higher-performance than an existing product, and it put on an equivalent package.</p>			
<b>Qualification Plan:</b> <p>Estimated date for qualification completion: 31 March 2015</p> <p>Refer to the attachment.</p> <p><i>To access file attachments on pdf copy of PCN, please be guided by the steps below:</i></p> <ol style="list-style-type: none"> <li>1. Download pdf copy of the PCN to your computer</li> <li>2. Open the downloaded pdf copy of the PCN</li> <li>3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field</li> <li>4. Then click on the attached file/s</li> </ol>			
<b>List of Affected General Parts:</b> <p>LE25S81MCS00TWG</p>			



---

**List of Affected Customer Specific Parts:**

LE25S81MCS01TWG  
LE25S81MCS02TWG  
LE25S81MCS03TWG  
LE25S81MCS04TWG  
LE25S81MCS05TWG  
LE25S81MCS06TWG